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	Filing Date		2002-01-22	
	First Named Inventor	Mou-Shiung Lin		
	Art Unit	2813		
	Examiner Name	Mitchell, James M		
Attorney Docket Number		MEGP0009USA		

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1	JACOB MILLMAN, Digital and Analog Circuits and Systems, MICRO ELECTRONIC, March 1979, p 115 & p 167, Sec 4-11 & Sec 6-1, McGraw-Hill College.	<input type="checkbox"/>
2	Rao R. Tummala, Eugene J. Rymaszewski & Alan G. Klopfenstein, MICROELECTRONICS PACKAGING HANDBOOK (Second Edition), Technology Drivers Part I, January 31, 1997, p 12-13, p 64-65, p 82-87, p 133, An overview & 8-2 chip-level interconnection evolution, Springer.	<input type="checkbox"/>
3	John H. Lau & S.W. Ricky Lee, Chip Scale Package, General Electric's Chip-On-Flex Chip Scale Package (COF-CSP), February 28, 1999, P0156-161, Chapter ten, McGraw-Hill Professional.	<input type="checkbox"/>

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